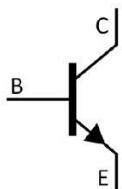


Silicon NPN transistor in a TO-18 Plastic Package.

High V_{CEO} , Large DC current, high f_T , low $V_{CE(sat)}$.

Low power audio amplifier, high speed switching applications.



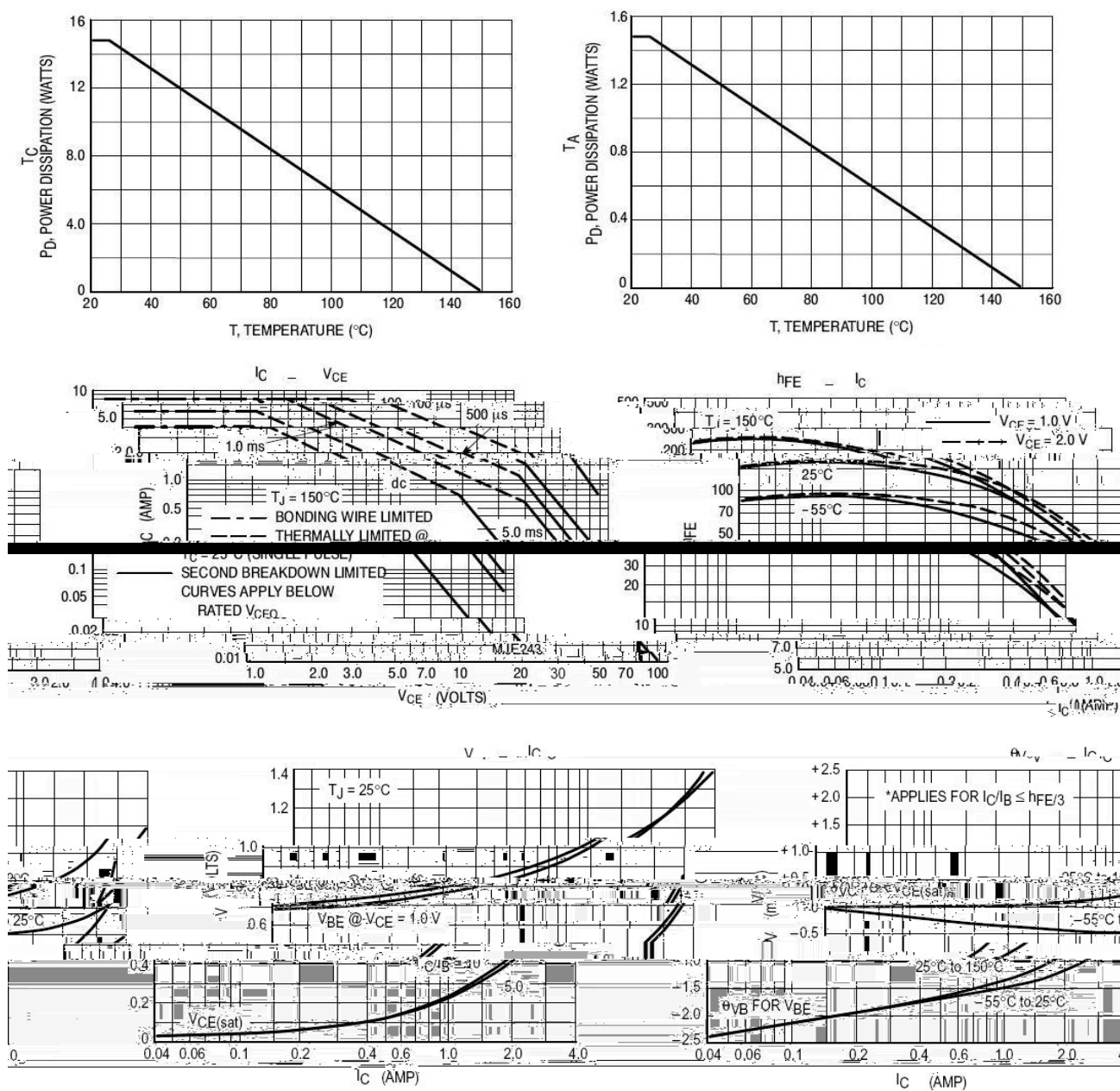
PIN1 Emitter PIN 2 Collector PIN 3 Base

/ h_{FE} Classifications & Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	100	V
Collector to Emitter Voltage	V_{CEO}	100	V
Emitter to Base Voltage	V_{EBO}	7.0	V
Collector Current - Continuous	$I_{C(1)}$	4.0	A
	$I_{C(2)}$	8.0	A
Peak Collector Current	I_B	10	A
Collector Power Dissipation	P_D	1.5	W
Collector Power Dissipation	$P_D(T_c=25^\circ C)$	15	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55~150	

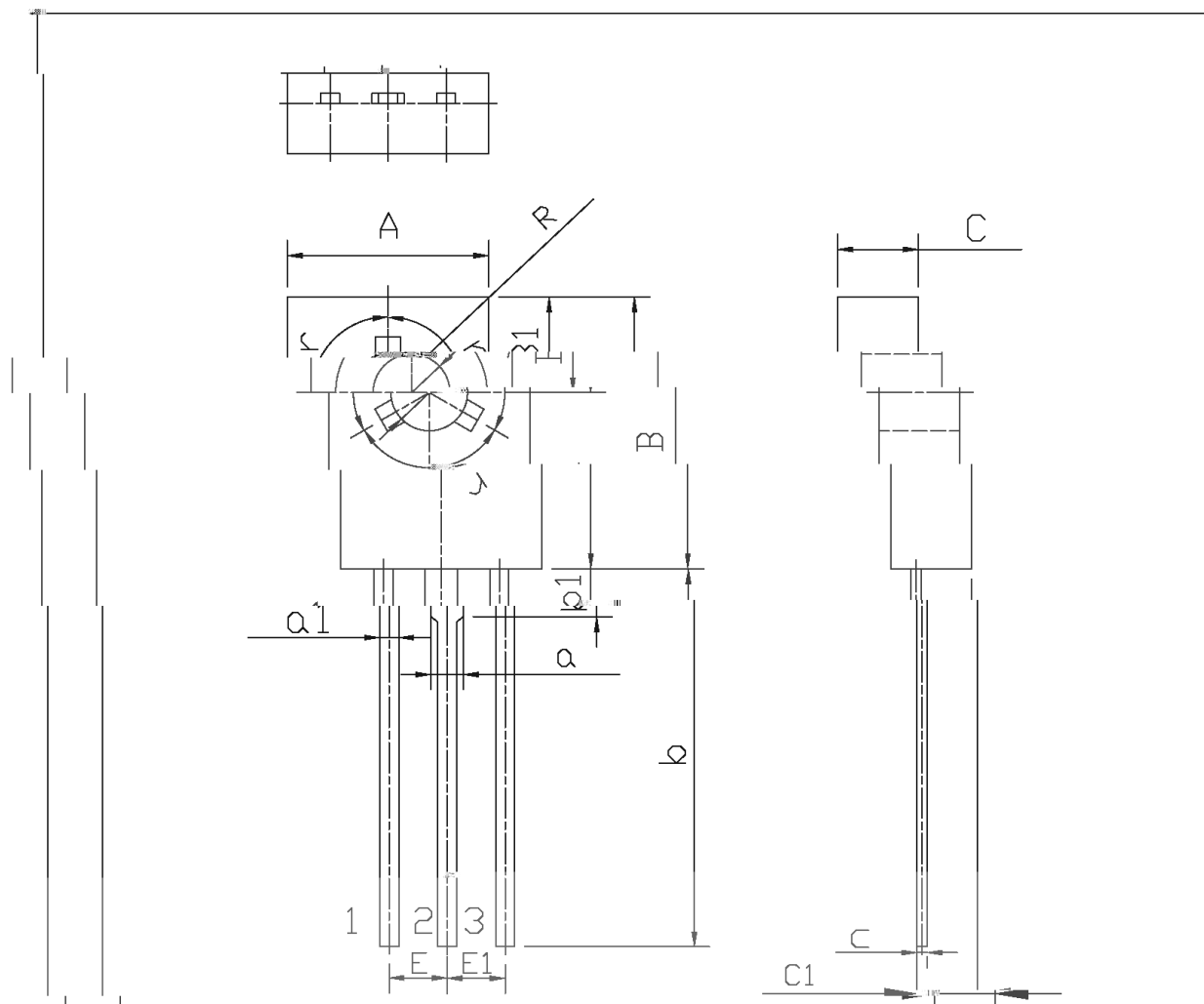
/ Electrical Characteristic Curve



/ Package Dimensions

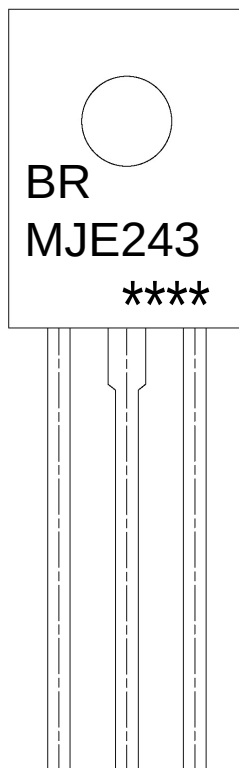
T□-126

单位: mm



Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
A	7.8	8.2	a1	0.66	0.86
B	10.6	11.0	E	2.1	2.5
B1	3.6	4.0	C	2.7	2.9
R	2.9	3.3	C1	1.57	1.77
b	14	16	c	0.2	0.6
b1	1.9		a	1.37	
E1	2.1	2.5	r	120°	

/ Marking Instructions



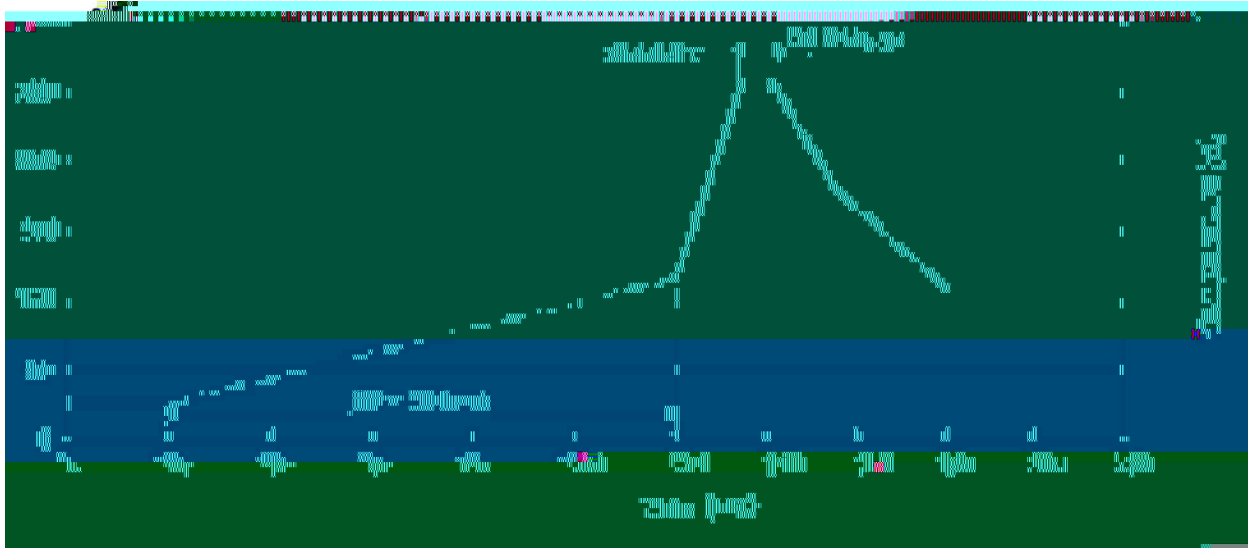
Note:

BR: Company Code

MJE243: Product Type.

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box